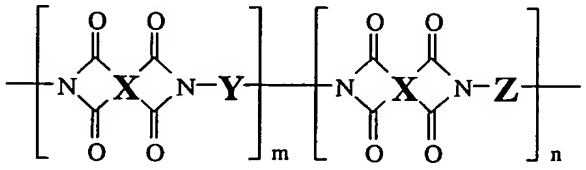
CLAIMS:

1. A wafer dicing/die bonding sheet comprising a backing member, an adhesive layer formed thereon, and a protective member for protecting the adhesive layer,

said adhesive layer being made of an adhesive composition comprising a phenolic hydroxyl radical-bearing polyimide resin, an epoxy resin, and an epoxy resin curing agent, the ratio of the total weight of the epoxy resin and the epoxy resin curing agent to the weight of the polyimide resin being from 0.1:1 to 3:1.

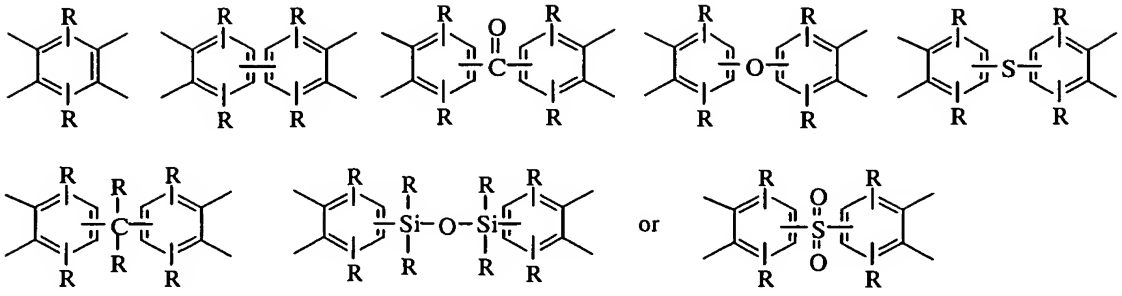
2. The wafer dicing/die bonding sheet of claim 1 wherein said adhesive composition is a heat resistant polyimide resin composition comprising a polyimide resin having phenolic hydroxyl radicals in or at the ends of the polyimide skeleton, comprising recurring units of the structural formula (1) or (2) shown below and prepared using a diamine or monoamine bearing an aromatic ring having an amino radical and another aromatic ring having a phenolic hydroxyl radical, an epoxy resin having at least two glycidyl radicals, and an epoxy resin curing agent,
the structural formula (1) or (2) being:



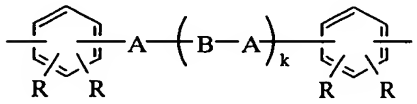
(1)

wherein X is at least one tetravalent organic radical as shown below, Y is a divalent organic radical comprising at least one diamine residue (Y_1) having a phenolic hydroxyl radical as shown below and at least one aromatic diamine residue (Y_2) as shown below, the molar ratio of $Y_1/(Y_1+Y_2)$ being from 0.01 to 1, Z is at least one siloxane diamine residue as shown below, m and n are natural numbers satisfying $0.1 \leq m/(m+n) \leq 0.99$ and $10 \leq m+n \leq 500$,

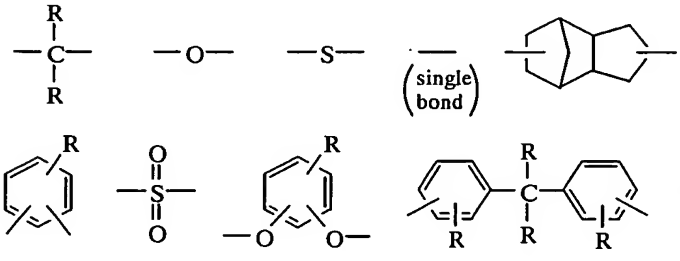
X =



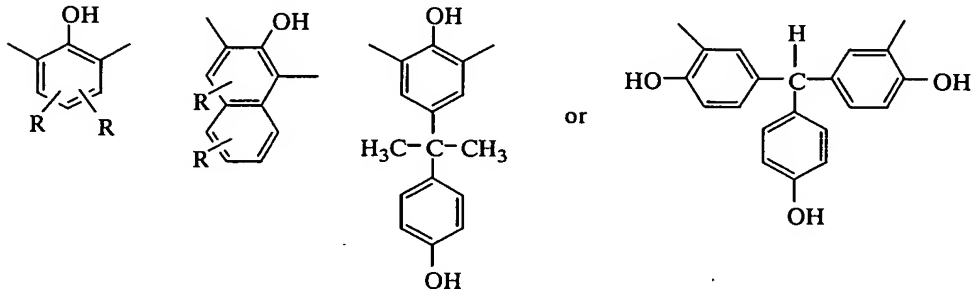
Y_1 =

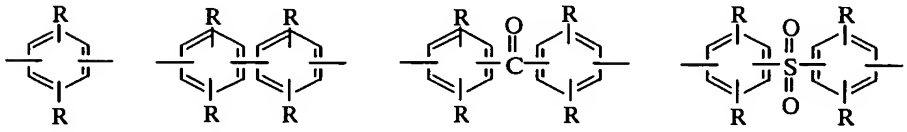


A =

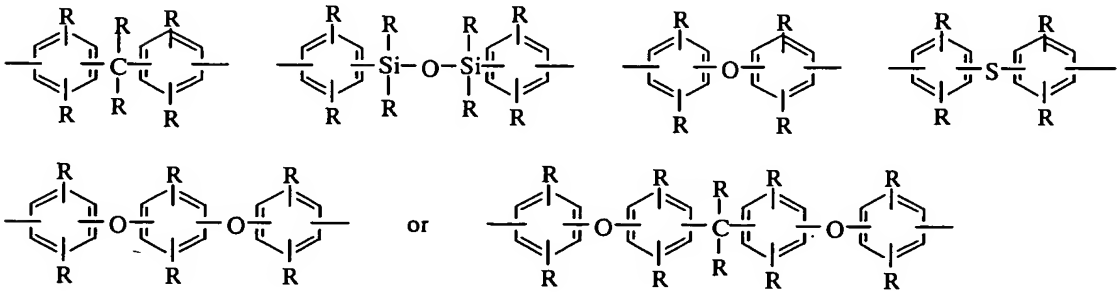


B =

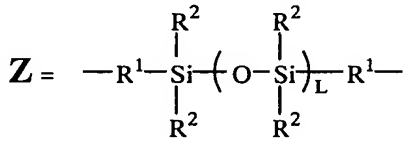




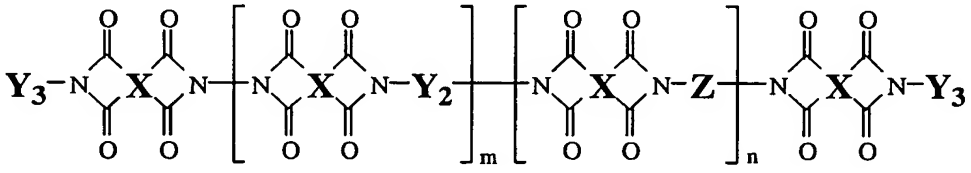
Y_2 =



wherein k is a natural number of 1 to 5, R is each independently a hydrogen atom, a halogen atom or a substituted or unsubstituted monovalent hydrocarbon radical having 1 to 8 carbon atoms,



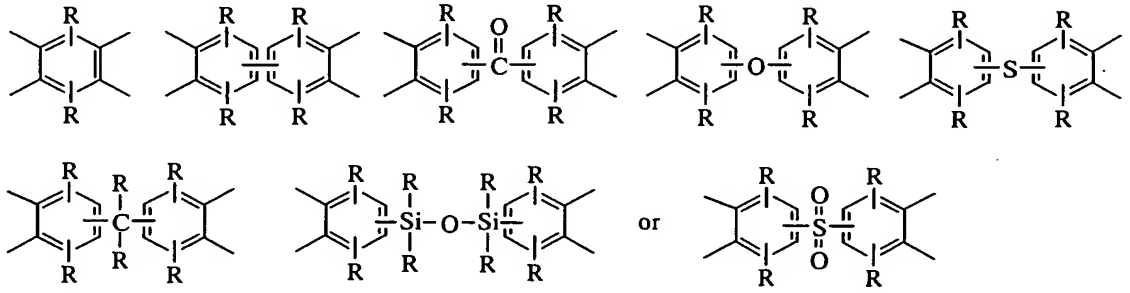
wherein R^1 is each independently an alkylene radical of 1 to 8 carbon atoms or arylene radical, R^2 is each independently an alkyl or alkoxy radical of 1 to 8 carbon atoms which may be branched, or aryl radical, and L is an integer of 4 to 60,



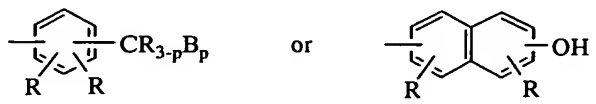
(2)

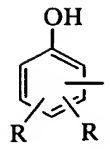
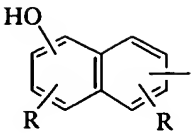
wherein X is at least one tetravalent organic radical as shown below, Y_2 is a divalent organic radical comprising at least one aromatic diamine residue as shown below, Y_3 is a monovalent organic radical comprising at least one aromatic amine residue having a phenolic hydroxyl radical as shown below, Z is at least one siloxane diamine residue as shown below, m and n are natural numbers satisfying $0.1 \leq m/(m+n) \leq 0.99$ and $10 \leq m+n \leq 500$,

X =

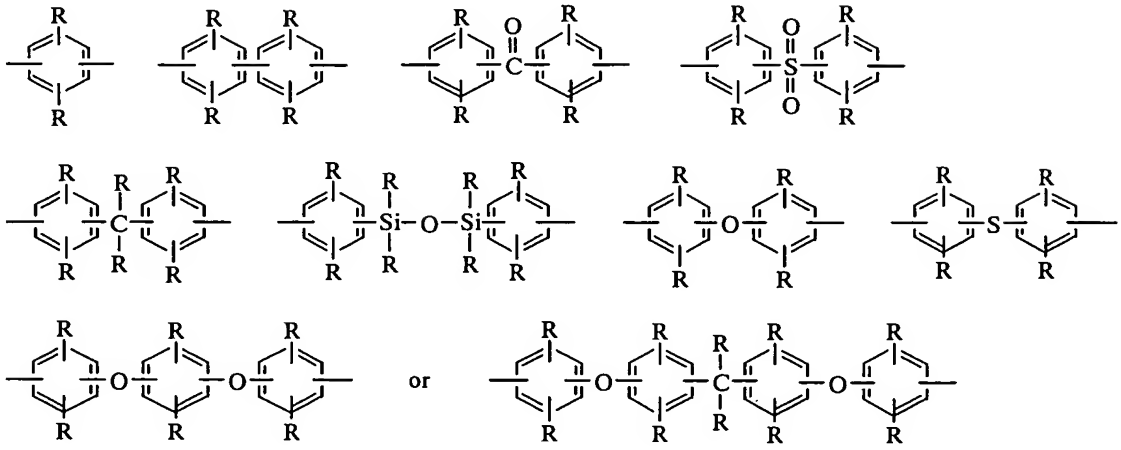


Y_3 =

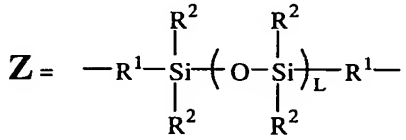


B =  or 

wherein p in Y_3 is a natural number of 1 to 3,

Y_2 = 

wherein R is each independently a hydrogen atom, a halogen atom or a substituted or unsubstituted monovalent hydrocarbon radical having 1 to 8 carbon atoms,

Z = 

wherein R^1 is each independently an alkylene radical of 1 to 8 carbon atoms or arylene radical, R^2 is each independently an alkyl or alkoxy radical of 1 to 8 carbon atoms which may be branched or aryl radical, and L is an integer of 4 to 60.

3. The wafer dicing/die bonding sheet of claim 1 wherein said adhesive composition further comprises a silane coupling agent.